

CBRS Chip Antenna
Off Ground SMT Monopole
W3154: 3500 – 3980 MHz



Features:

-  Compact size 3.20 x 1.56 x 1.10 mm (WxLxH)
-  Low weight 33 mg
-  Fully SMD compatible
-  MSL: 1
-  Tape and reel packing

Applications;

-  CBRS B48
-  C-band B43
-  Portable radios
-  IoT, safety and security -devices

ELECTRICAL SPECIFICATIONS +25° C

W3154

Antenna type	Nominal Impedance	Polarization	Radiation pattern	Power withstanding
Monopole	50Ω	Linear	Omni	3W

Frequency (MHz)	3500 - 3980
Return Loss(dB)	< 6
Peak Gain (dBi)	2.5
Efficiency (%)	65

MECHANICAL SPECIFICATIONS

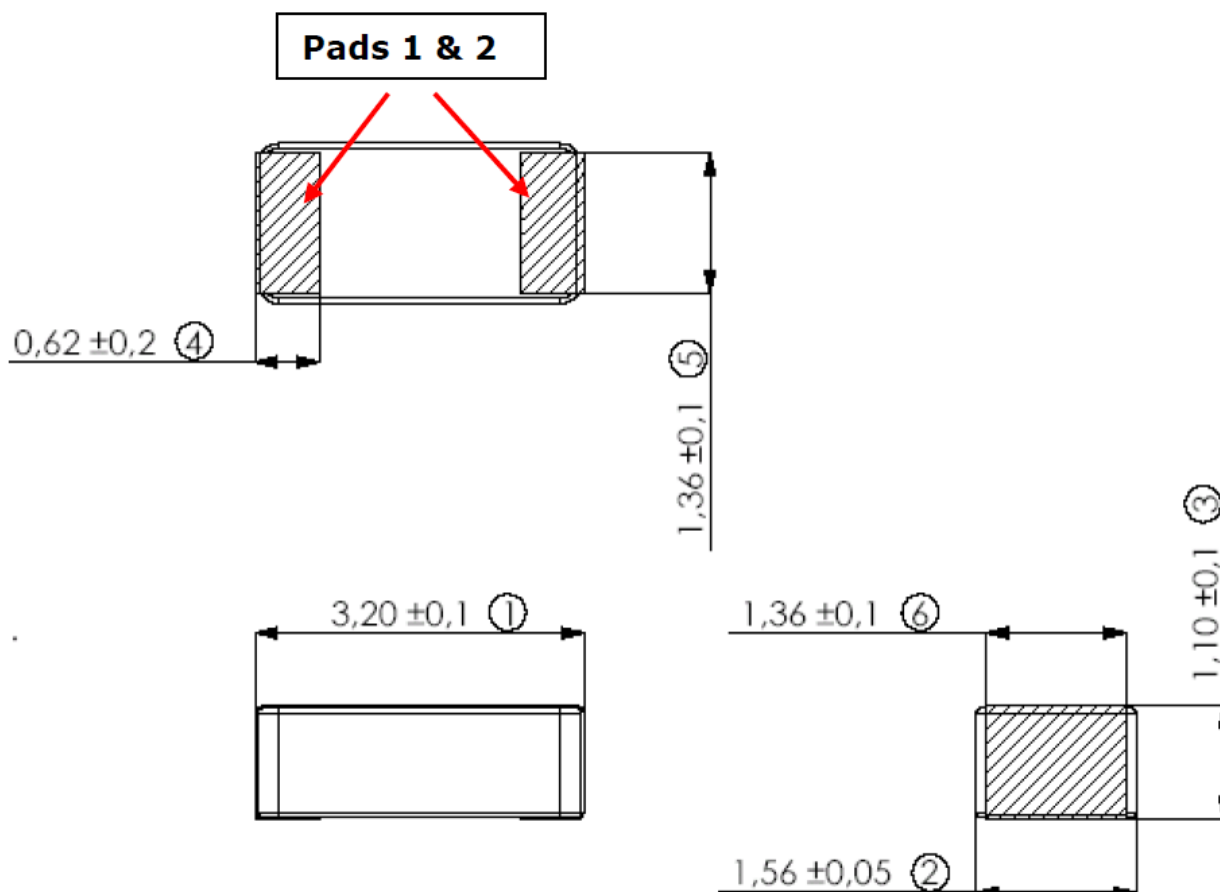
Orderable P/N: W3154

Dimension (Length x Width x Height)	Material	Color
3.2mm x 1.56mm x 1.1mm (.126" x .061" x .043")	ceramic	grey

ENVIRONMENTAL SPECIFICATIONS

W3154

Storage Temperature	Operating Temperature	MSL-Level	RoHS Compliant
-40/+85° C	-40/+85° C	1	Yes



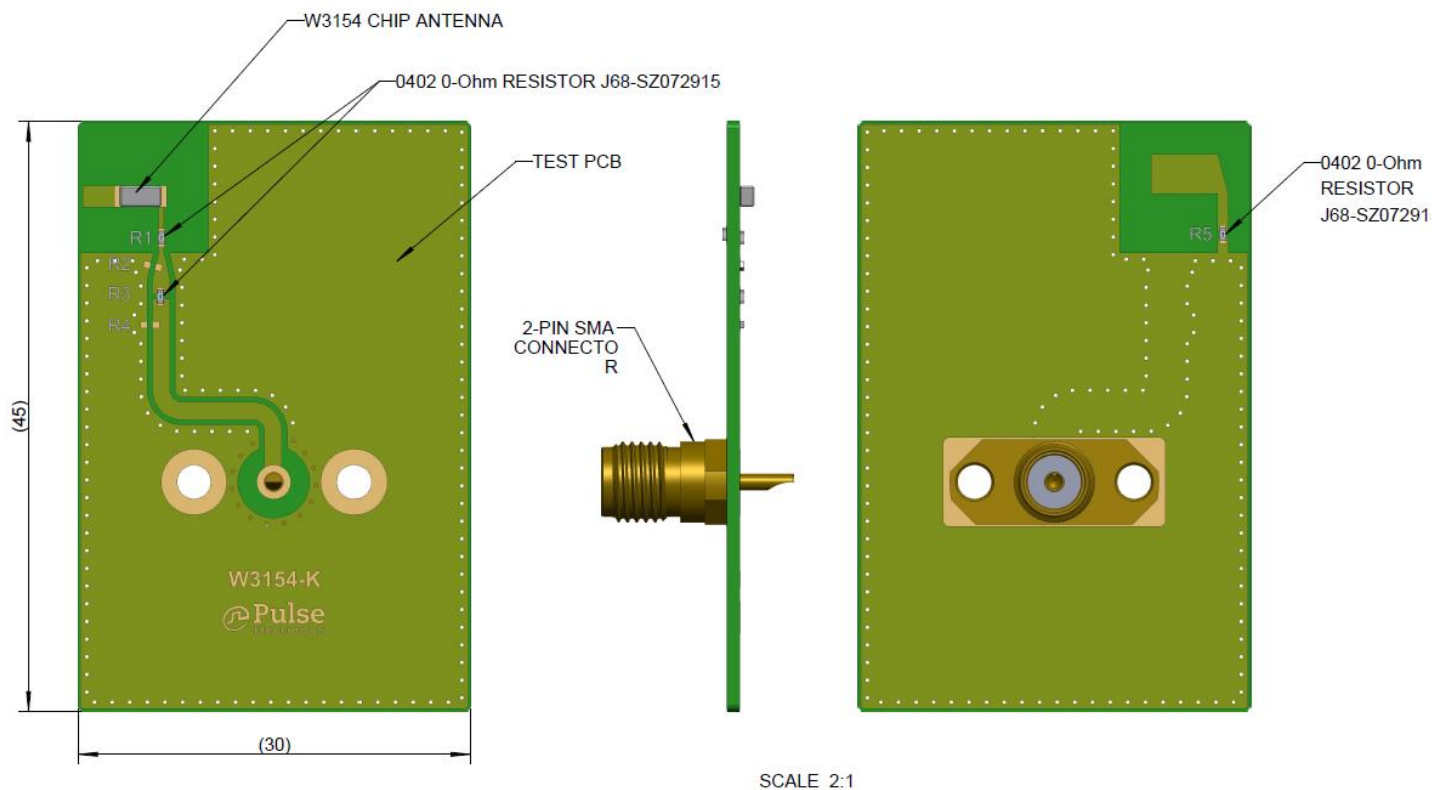
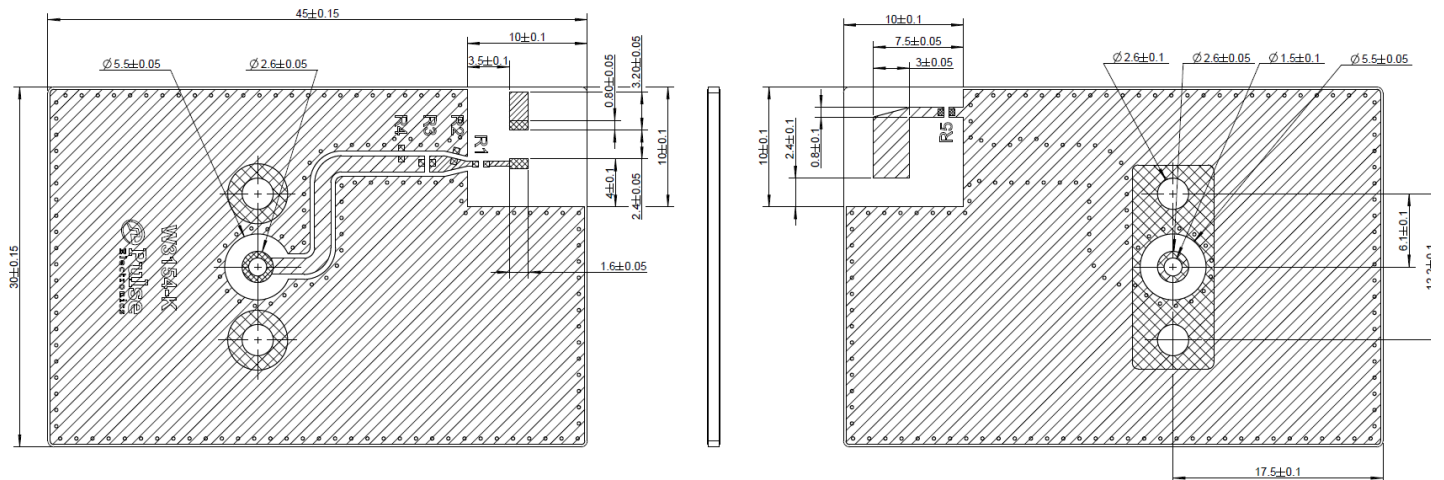
Antenna features

No.	Terminal Name	Terminal Dimensions
1	Feed / Support	0.62 x 1.36 mm
2	Feed / Support	0.62 x 1.36 mm

Antenna is symmetrical.
Either of terminals 1 or 2 can be Feed / Support

Terminal Configuration, PCB Layout

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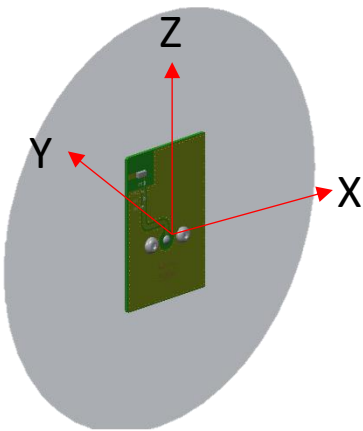
Test Setup

General / Chamber Setup

- Measured at Pulse Finland (MVG SGL24 Chamber)
- Measured with W3154-Kit



Measurement setup



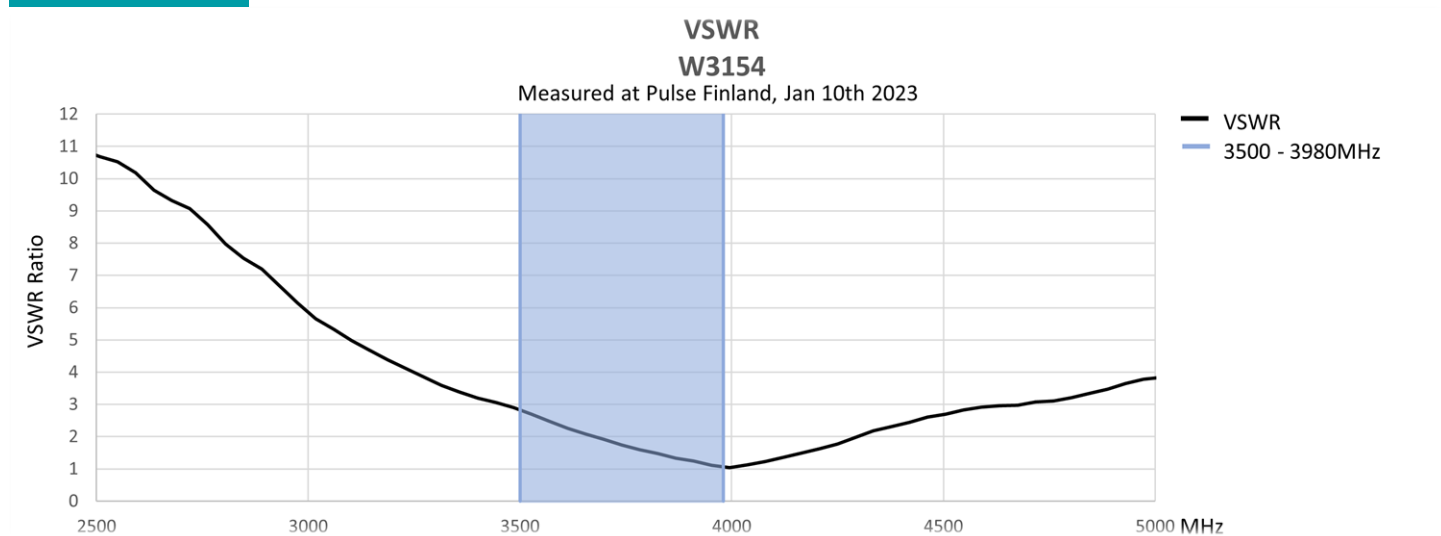
Chamber coordinate system

	Value	Component type
R1	0 - ohm	J68-SZ072915
R2	None	
R3	0 - ohm	J68-SZ072915
R4	None	
R5	0 - ohm	J68-SZ072915

Evaluation board matching component values

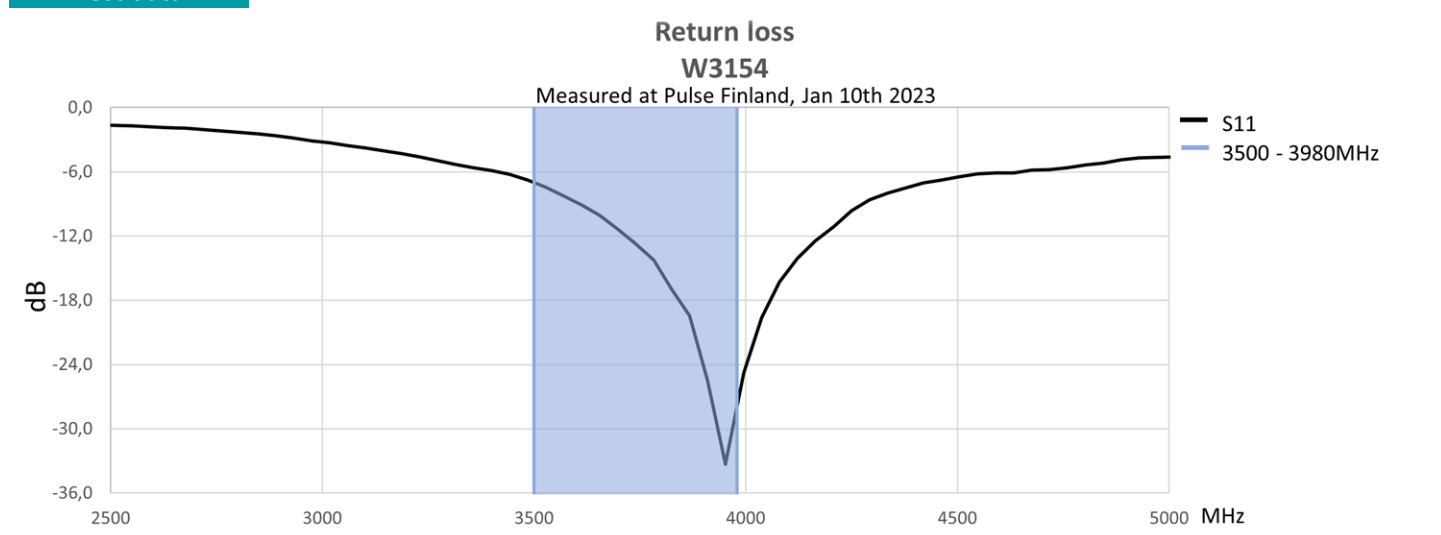
Charts - VSWR

Test data



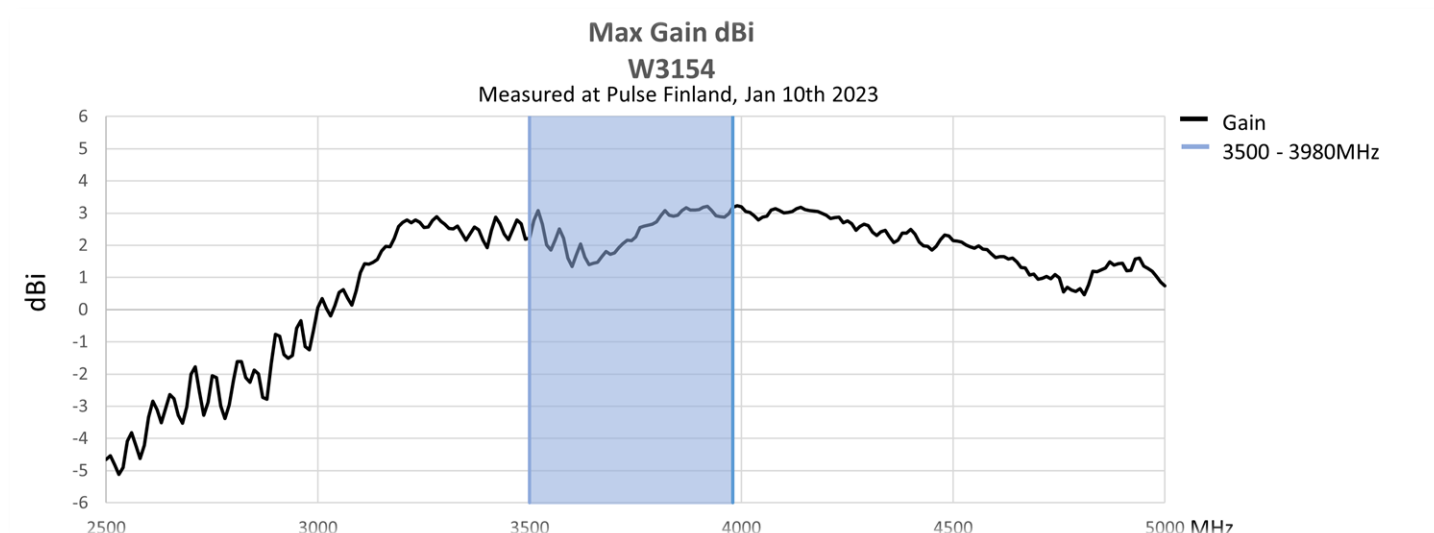
Charts - Return loss

Test data



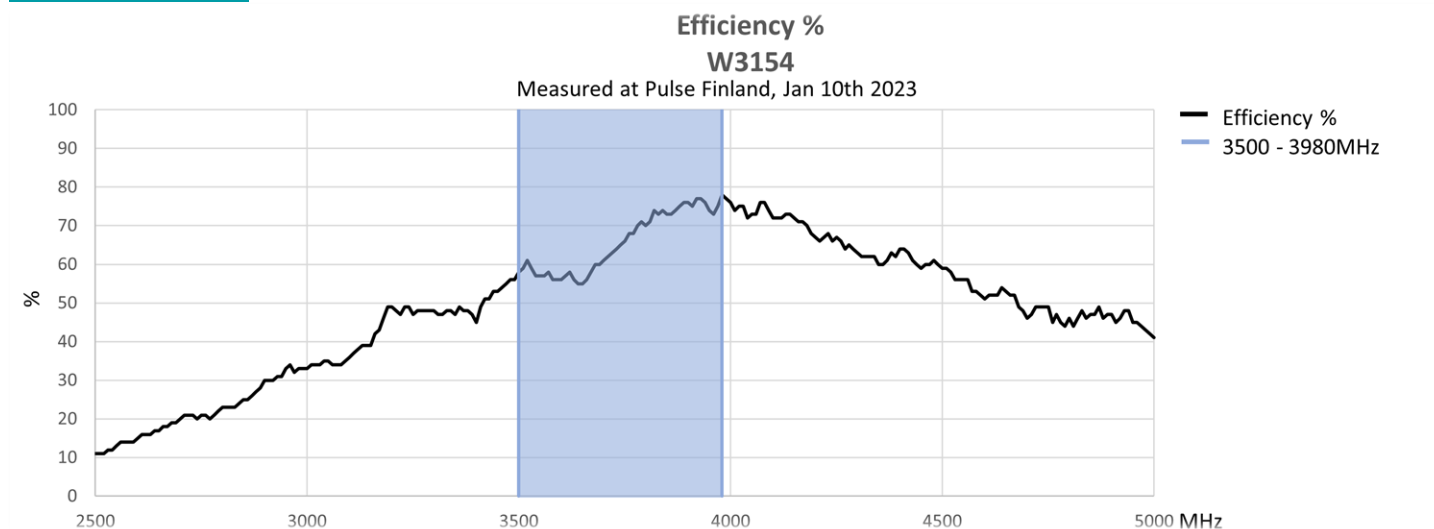
Charts – Max Gain dBi

Test data



Charts - Efficiency

Test data



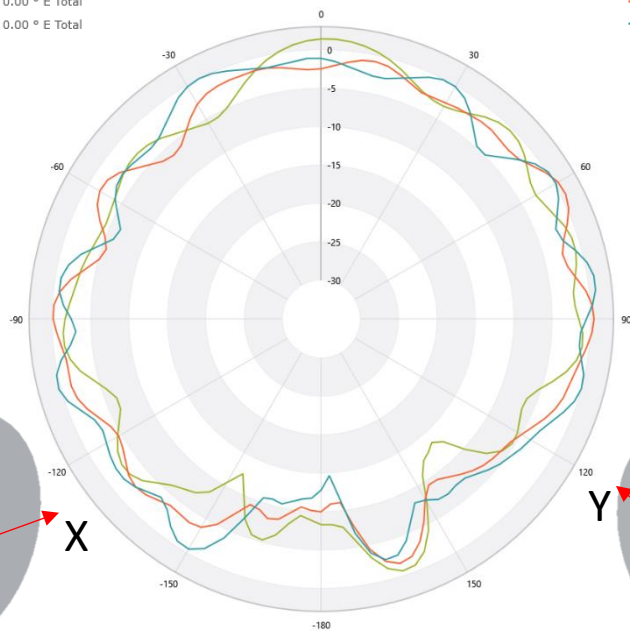
Radiation Patterns

XZ-plane

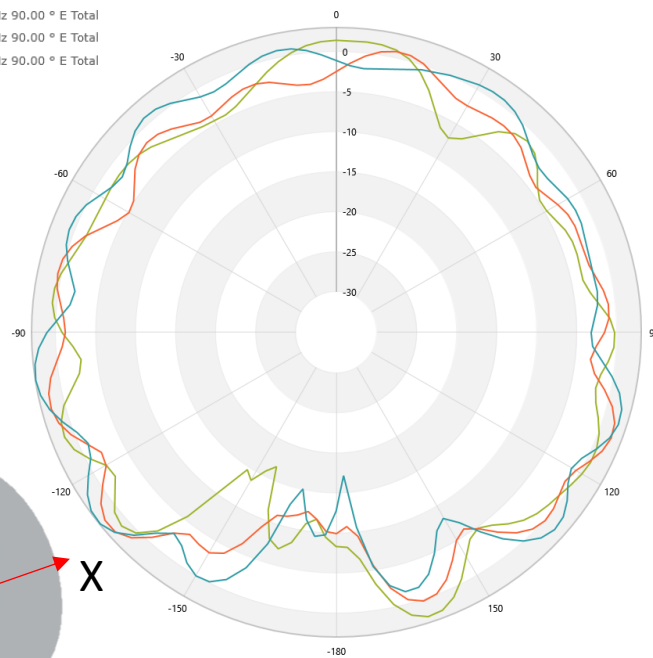
YZ-plane

Test data

— 3500.00 MHz 0.00 ° E Total
— 3750.00 MHz 0.00 ° E Total
— 3980.00 MHz 0.00 ° E Total



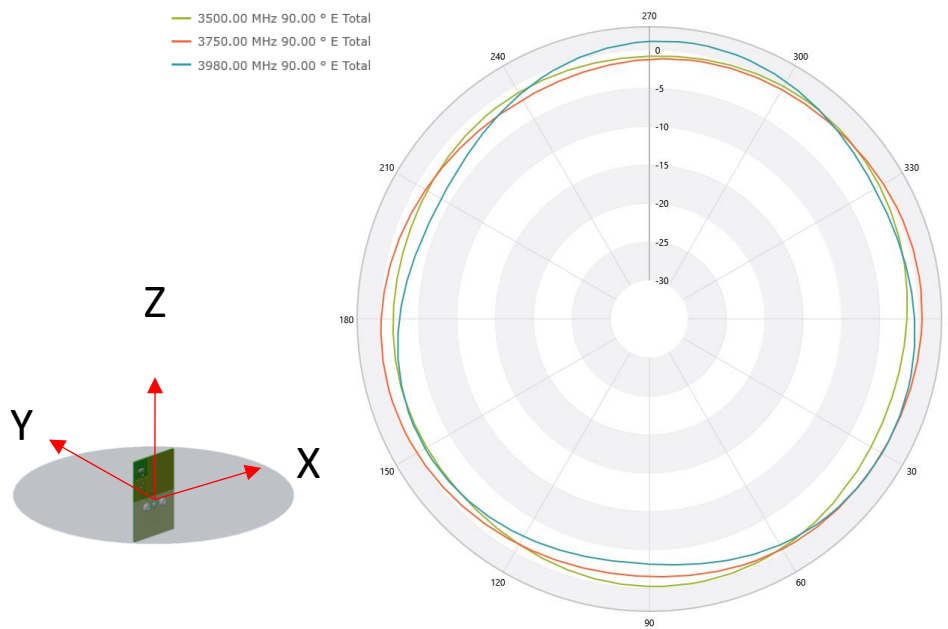
— 3500.00 MHz 90.00 ° E Total
— 3750.00 MHz 90.00 ° E Total
— 3980.00 MHz 90.00 ° E Total



XY-plane

Test data

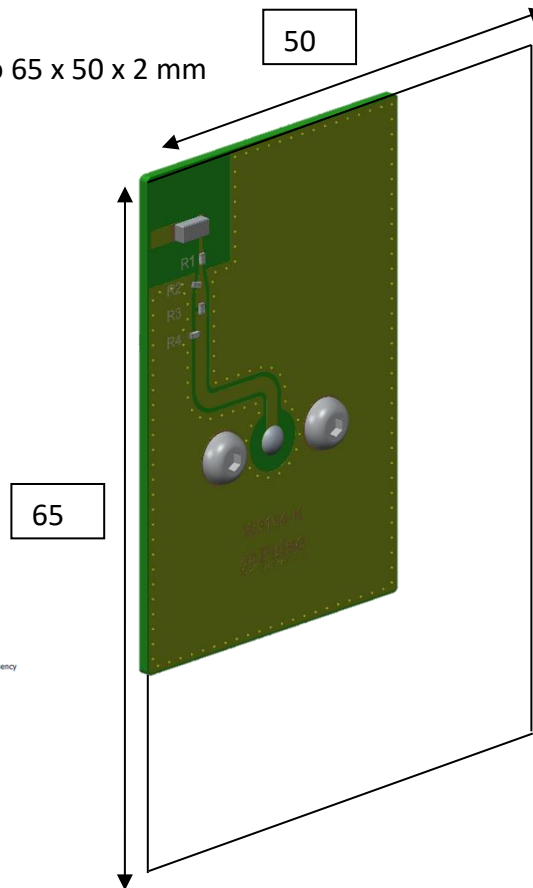
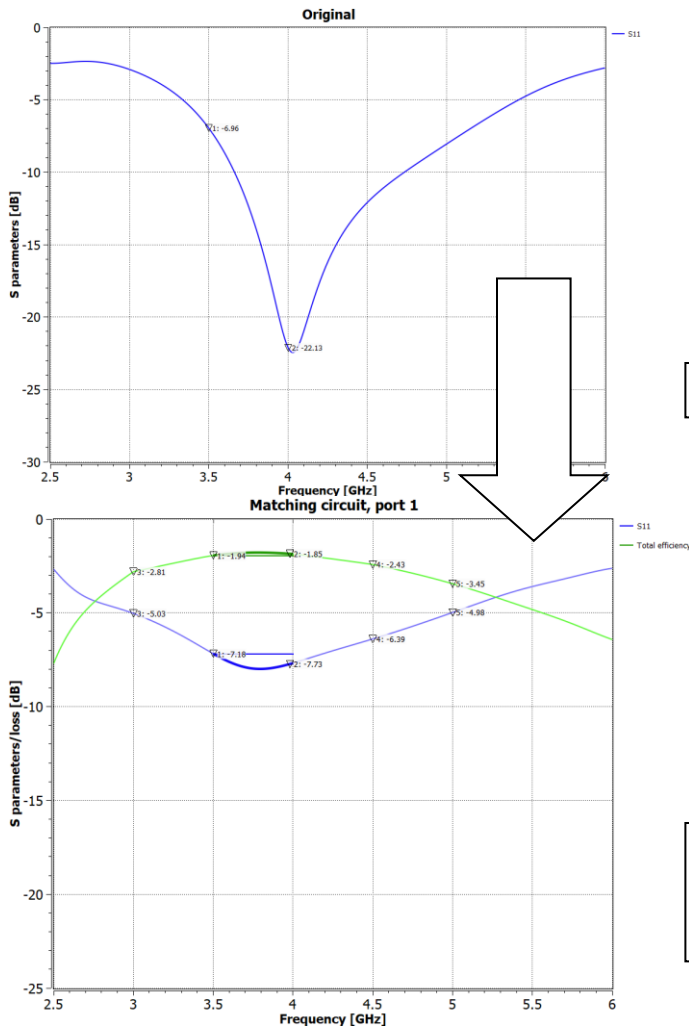
— 3500.00 MHz 90.00 ° E Total
— 3750.00 MHz 90.00 ° E Total
— 3980.00 MHz 90.00 ° E Total



Tuning example

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- Board size increased from 45 x 30 x 1 mm to 65 x 50 x 2 mm



Note: simulation model results vary from actual real life measurement results.

	Value	Component type
R1	0 - ohm	J68-SZ072915
R2	None	
R3	0 - ohm	J68-SZ072915
R4	None	
R5	0 - ohm	J68-SZ072915

Move resonance downward - topology

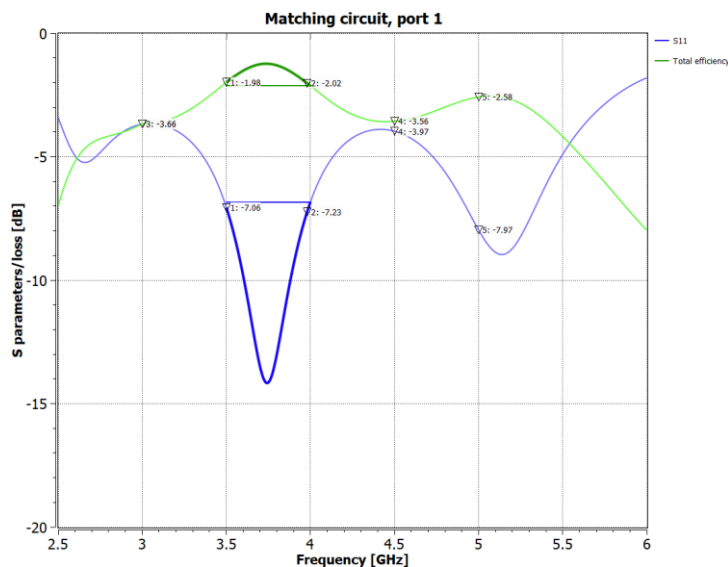
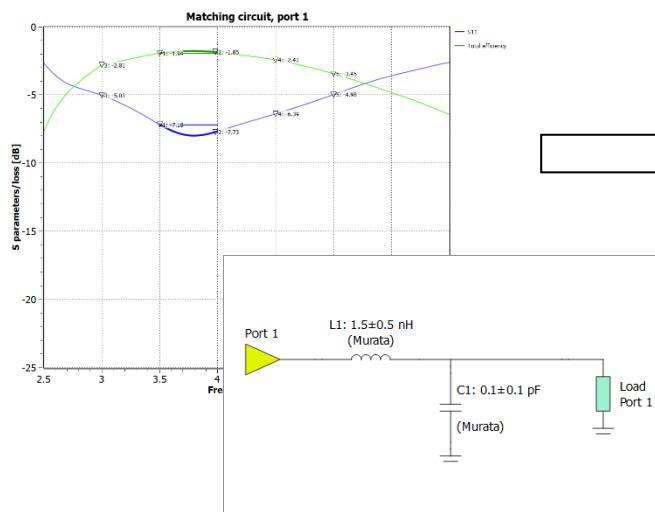
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Try this configuration if resonance is too high.

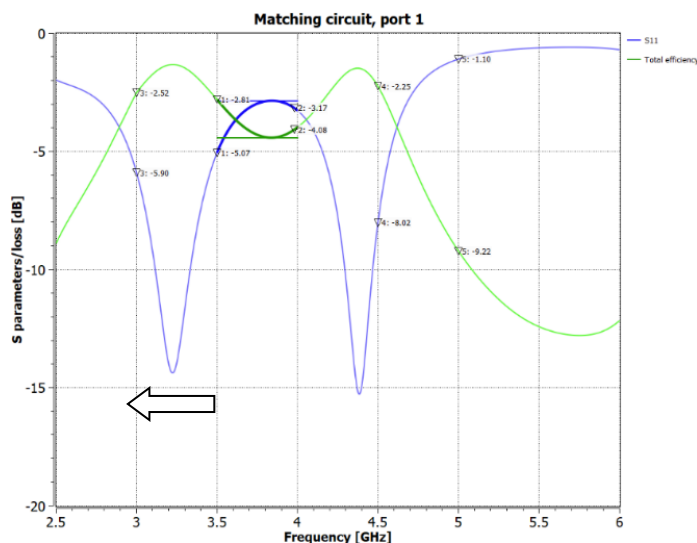
Matching circuit generated from s-parameters by Optenni, using 2 components from Murata LQW15AN- and GJM15 series components.

R3 on eval board = Inductor L1

R2 on eval board = Capacitor C1



Increase capacitor C1 value to move resonance **downward**



Move resonance upward - topology

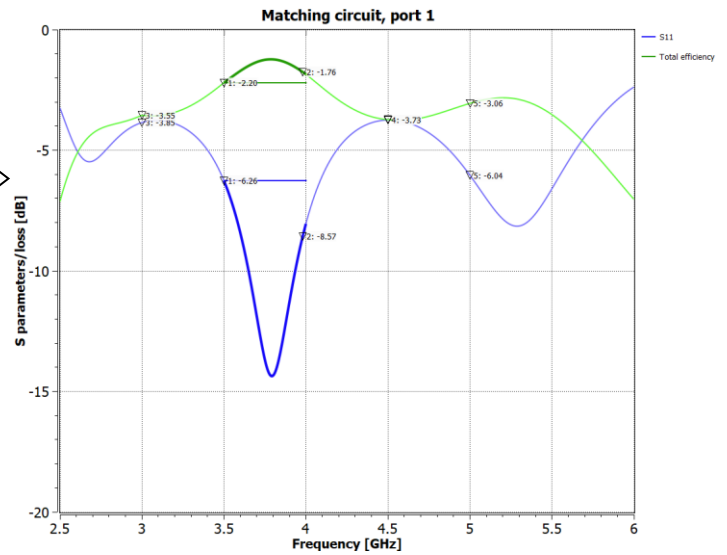
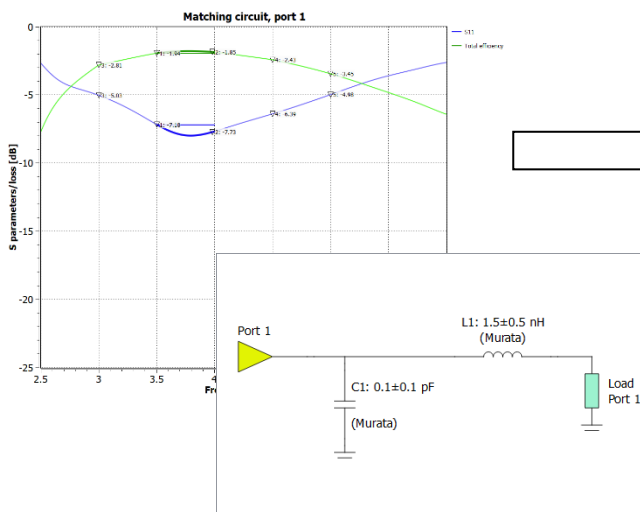
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Try this configuration if the resonance is too low.

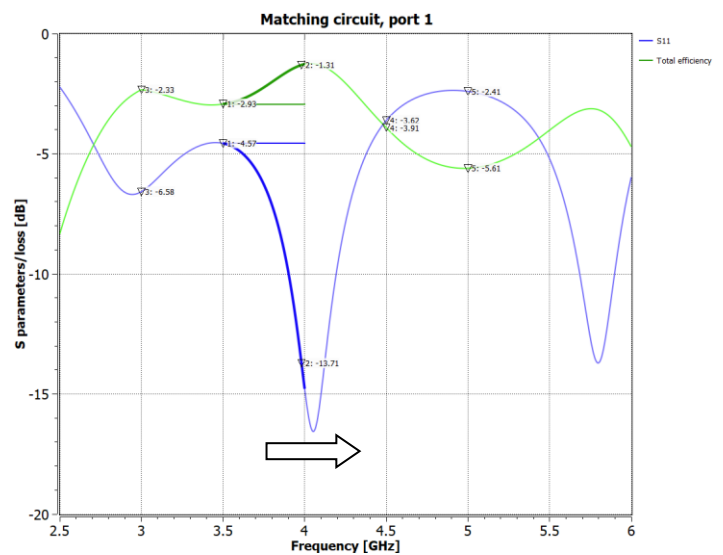
Matching generated from s-parameters by Optenni, using 2 components from Murata LQW15AN- and GJM15 series components

R4 on eval board = Capacitor C1

R3 on eval board = Inductor L1



Increase capacitor C1 value to move resonance **upward**



Storage condition recommendation

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Storage time

Products should be used within 6 months from the day of manufacturers packaging even when they are stored under below mentioned conditions. Longer storage period may decrease the component solderability.

Storage environmental conditions

To maintain solderability of Pulse ceramic products care must be taken to control the storage and use conditions:

- Do not store or use products in a corrosive atmosphere, especially where chloride, sulphur or sulfide, alkali or acid salts exist in the air. Corrosive gases may cause oxidation of electrodes and reduce solderability
- Keep temperature and humidity stable and do not exceed the below mentioned minimum and maximum conditions: Temperature: -10 to +30 Deg C
Humidity: below 60% RH
- Do not store the products under direct sun light.

It is recommended to keep the products in manufacturers packing (tape&reel) until the time of assembly and soldering process. Air tight vacuum package is recommended in the conditions where it is know to be some corrosive gases.

Handling

Do not touch the components with bare hands. Protective gloves must be used to prevent contamination of terminals which may cause reduced solderability. Do not touch or damage the silver plated surface by any sharp objects. Soft materials (plastic, wood etc.) must be used if tweezers or other tools are used to pick the components. Avoid any excess mechanical shock or vibration during storage and handling.

Reflow soldering profile

W3154

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

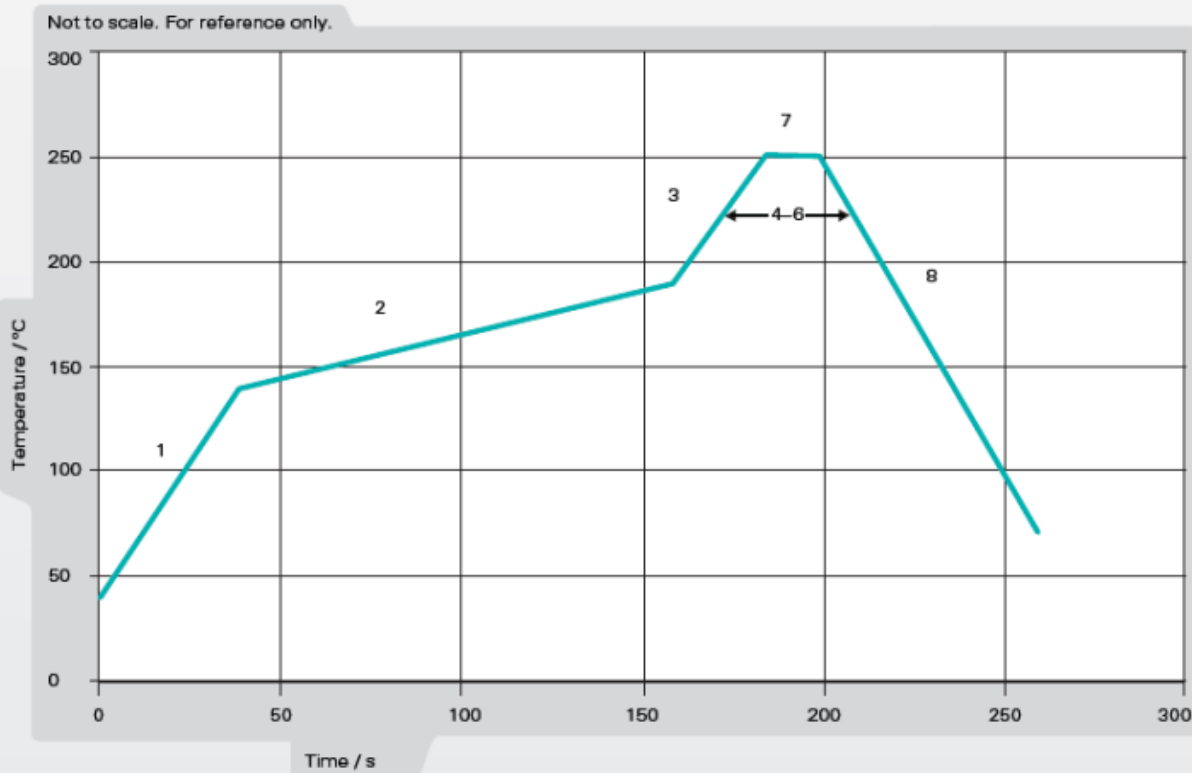


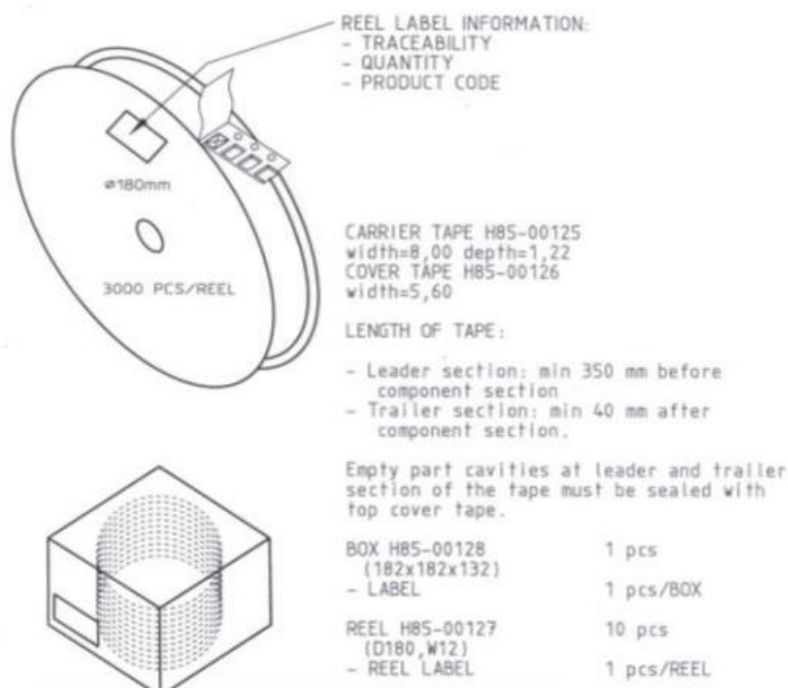
Figure 2. Maximum temperature profile recommendation for reflow soldering process

Packing

W3154

Tape and reel packing is used.

3000pcs antenna/reel, 10 reels/inbox, 2 inbox(60000pcs antenna)/outbox.



LEVEL

1

NOT MOISTURE SENSITIVE

These Devices do not require special storage conditions provided:

1. They are maintained at conditions equal to or less than 30°C and 85% RH.
2. They are solder reflowed at a peak body temperature which does not exceed 260°C.

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

For More Information:

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